

REMARKS

Claim Rejections

Claims 1, 3-6, 10 and 14 are rejected under 35 U.S.C. §102(e) as being anticipated by Kim et al. (US 6,774,543). Claims 2 and 13 are rejected under 35 U.S.C. §103(a) as being unpatentable over Kim et al. and Reisenauer et al. (US 6,161,910). Claim 12 is rejected under 35 U.S.C. §103(a) as being unpatentable over Kim et al.

Drawings

It is noted that the Examiner previously accepted the drawings as originally filed with this Application.

Claims

Regarding the rejections of Claims 1, 3-6, 10 and 14 under 35 U.S.C. §102(b) as being anticipated by Kim et al., Applicant submits the following arguments (1-6) for consideration.

1. Regarding claim 1, according to the description lines of column 4, lines 21-29 of Kim et al., spacers (26), can be formed with adhesive on both sides, disposed between the PDP (20) and the chassis base (22), and are applied for supporting a gap between PDP 20 and chassis base 22. **The spacers (26) are apart from each other (disposed at the corners of the chassis base 22) so that they cannot be divided into an outer closed portion and an inner portion by an annular channel.** From the above analyses, we believe that **it is impossible to form an outer closed portion and an inner portion at the same time** in accordance with the description of Kim et al. In the present application, however, the laminar attachment structure **itself comprises** an inner channel which divides the laminar attachment structure into an outer closed portion and an inner portion, which communicates with an external environment via the vacuum-pumping aperture after the laminar attachment being connected to the PDP and the heat-dissipating plate.

Therefore, Applicant submits Kim et al. is substantially different from the present invention in structure.

In addition, the spacers (26) in Kim et al. are just applied for supporting without any heat conduction property, but the laminar attachment structure in the present invention are applied for **thermally connecting** the PDP to the heat-dissipating plate. Thus, the **laminar attachment structure itself** should be provided with heat conduct performance.

Nevertheless, Applicant emphasizes that Kim et al. fails to disclose the element "vacuum-pumping aperture(s)" in heat-dissipating plate, instead, the item 24 is heat conductive media for dissipating the heat generated in PDP. Thus, we believe that it is impossible for Kim et al. to have the laminar attachment structure having an annular channel communicating with the external environment through the vacuum-pumping aperture(s), such as vacuum suckers (6) as described in the paragraph 19 of the present invention, formed at the heat-dissipating plate. Therefore, the applicant respectfully traverses the viewpoint "under no basis" that the laminar attachment structure provided such as the spacers 26 in Kim et al. communicates with the vacuum-pumping aperture(s). Applicant submits that Claim 1 of the present application is not anticipated by Kim et al. Please kindly and carefully take it into reconsideration.

2. Regarding claim 3, please kindly refer to the Argument 1, the laminar attached structure of the present invention is further determined as an adhesive double tape for thermally connecting the heat-dissipating plate to the plasma display panel (PDP). In other words, the heat-dissipating plate is **indirectly connected** with the PDP, i.e., **the heat-dissipating plate is connected to one surface of the adhesive double tape, and PDP is connect to the other surface of the adhesive double tape**, so that it is different from the spacers (26). In Kim et al., spacers can be formed with adhesive on both sides, and applied for supporting PDP (20) to the chassis base (22) to make the heat conductive members (24a-24e) dispose between the PDP (20) and the chassis base (22), i.e. the **PDP (20) directly touch with the heat conductive members (24a-24e) without through the laminar attachment structure**.

3. Regarding claim 4, please kindly refer to the Argument 1, the spacers (26) are used for supporting PDP (20) to the chassis base (22) in the Kim et al. without any other function, while the **guide trench** as mentioned in the present invention is applied for communicating with the vacuum-pumping aperture so that vacuum-pumping can be carried out to exhaust air or bubble within the guide trench and aid absorbing the PDP to the heat-dissipating to provide well connection between PDP and heat-dissipating plate.

In addition, the trenches are formed between the areas of **the heat conductive members (24a-24e) in Kim et al., while the trench(es) is/are formed between the elements of the laminar attachment structure itself**, so that the trenches in Kim et al. are different from the trench(es) as provided in the present invention.

4. Regarding claim 5-6, please kindly refer to the Argument 1, **Applicant respectfully disagrees with the viewpoint that the heat-dissipating plate in Kim et al. provides any vacuum-pumping aperture.**

In addition to the preceding statement of the paragraph 19 of the present invention, through the means of pumping out the air within the closed loop (21), the substantial attached area of the back of the PDP (12) to the heat-dissipating metal plate (3) in the present invention can be increased more than 85% of the whole area, so that people skilled in these arts can easily realize that it does not only **improve the attachment performance between the PDP (12) and the heat-dissipating metal plate (3)**, but also **increase the efficiency of heat-dissipating**. Thus, Kim et al. still presents no evidence that at least one inner trench of the inner portion of the laminar attachment structure communicates with the external environment through at least one vacuum-pumping aperture formed at the heat-dissipating plate. Futher, Kim et al. still also presents no evidence that the air between the PDP (20), conductive media (24) and the chassis base (22) can be guide out by pumping to improve the attachment between the PDP and the heat-dissipating plate.

5. Regarding claim 10, **the strips of the Kim et al. are the heat conductive members (24a-24e)**, which does not belong to any part of the laminar attachment structure, while the strips of the present invention belong to the parts of the laminar attachment structure. Furthermore, **the trenches are formed between the areas of the heat conductive members (24a-24e)** in Kim et al., while **the guide trench** for guiding out air within the spaces of the strips is **formed between each pair of the neighboring strips**, which is **the part of the laminar attachment structure itself**.

In additional, the laminar attachment structure provided as spacers (26) in Kim et al. are just applied for supporting without any heat conduction property, but the laminar attachment structure in the present invention are applied for **thermally connecting** the PDP to the heat-dissipating plate. Thus, the **laminar attachment structure itself** should be provided with consideration of heat conduct performance.

Nevertheless, we **have to emphasize once more that Kim et al., fails to disclose the element “vacuum-pumping aperture(s)” formed at the heat-dissipating plate and fails to disclose that the closed region formed by sealing two ends of the guide trench, which is a part one the laminar attachment structure, communicating with the vacuum-pumping aperture(s) formed at the heat-dissipating plate**. Therefore, the applicant respectfully traverses the viewpoint that Kim et al. provides the laminar attachment structure, such as the spacers (26), communicates with the external environment through the vacuum-pumping aperture(s). The claim 10 of the present application is not anticipated by Kim et al.

6. Regarding claim 14, please kindly refer to the Argument 5, in the present invention, the laminar attached structure can be further determined as an adhesive double tape for **thermally connecting** the heat-dissipating plate to the plasma display panel, and forming the closed region to communicate with the vacuum-pumping aperture(s) and guide out air within the spaces of the strips. However, in Kim et al., the spacers (26), can be formed with adhesive on both surfaces, are applied for supporting the gap between the PDP (20) and the chassis base (22) only rather than for **thermally connecting** the PDP and the chassis base. Thus, **the**

functions of the adhesive double tape in the present invention are very different from the function of the spacers (26) in Kim et al.

Regarding the rejections of Claims 2 and 13 under 35 U.S.C. §103(a) as being unpatentable over Kim et al. in view of Reisenauer et al., Applicant submits the following argument (7) for consideration.

7. Regarding to claim 2 and 13, in Kim et al., the laminar attachment, as the mentioned spacers (26), is clearly determined being applied for supporting the gap between the PDP (20) and the chassis base (22), being formed with adhesive on both surfaces is one of the ways to support the gap between the PDP (20) and the chassis base (22). Hence, **there is no evidence**, at least from the contents of the whole specification and the claims, **determining that the laminar attachment, as the mentioned spacers (26), is applied as a heat-conduction element**. Since the spacers (26) are not a heat-conduction element, it would not have been obvious to anyone having ordinary skills to know that the laminar attachment structure can be applied as a thermal pad to aid dissipating heat form the PDP to the heat-dissipating plate. Furthermore, the characteristic of "**the thermal pad can be communicating with the vacuum-pumping aperture(s) for aiding thermally connecting the PDP with the heat-dissipating plate**" is also not obviously for anyone skilled in the arts.

Nevertheless, due to that the laminar attachment structure in the present invention, either being provided as a adhesive double tape or a thermal pad, are also applied for communicating with the external environment through the vacuum-pumping aperture(s), so that hot air between PDP and heat-dissipating plate can be guided out of the inner portion through the vacuum-pumping aperture(s) to perform well heat-dissipating performance. To the contrary, in Kim et al., hot air between PDP (20) and chassis base (22) can not be guided out. Any person having ordinary skill in the art would not been motivated to have the technical feature of the present application in view of Kim et al. and Reisenauer et al.

Applicant submits neither Kim et al. nor Reisenauer et al. disclose, or suggest a modification of their specifically disclosed structures that would lead one having ordinary skill in the art to arrive at Applicant's claimed structure. Applicant hereby

respectfully submits that no combination of the cited prior art renders obvious Applicant's remaining claims.

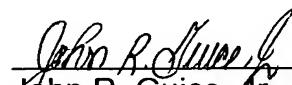
Summary

In view of the foregoing amendments and remarks, Applicant submits that this application is now in condition for allowance and such action is respectfully requested. Should any points remain in issue, which the Examiner feels could best be resolved by either a personal or a telephone interview, it is urged that Applicant's local attorney be contacted at the exchange listed below.

Respectfully submitted,

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By:


John R. Guice, Jr.
Reg. No. 39,699

TROXELL LAW OFFICE PLLC
5205 Leesburg Pike, Suite 1404
Falls Church, Virginia 22041
Telephone: 703 575-2711
Telefax: 703 575-2707

CUSTOMER NUMBER: 40144